

Clean Version Of Amended Claims

34. (amended) A test fixture for testing a semiconductor die comprising:

a first plate for receiving the die;

a second plate attached to the first plate for retaining the die therebetween; and

a tape placed between the first plate and the second plate for electrically connecting the die to test circuitry, the tape comprising a plastic film, a bump on the film for physically and electrically contacting a contact on the die, a conductive trace on the film in electrical communication with the bump, and an electrical connector in electrical communication with the trace and connectable to the test circuitry;

with the connector, and at least a portion of the trace extending beyond a confine of the fixture, and with the bump, the trace, and the connector configured to provide a direct electrical path from the test circuitry to the contact on the die.

35. (amended) The fixture of claim 34 wherein the film comprises polyimide.

39. (amended) A test fixture for testing a semiconductor die comprising:

a first plate for receiving the die;

a second plate attached to the first plate for retaining the die on the first plate; and

a tape for electrically connecting the die to test circuitry, the tape comprising a plastic film, a bump on the film for physically and electrically contacting a contact on the die, a conductive trace on the film in electrical communication with the bump, and an electrical connector in electrical communication with the trace and connectable to the test circuitry;

with a first portion of the film placed between the first plate and the second plate and biased against the die;

with a second portion of the film and the connector extending beyond a confine of the fixture, and with the bump, the trace and the connector providing a direct electrical path from the test circuitry to the contact on the die.

43. (amended) A test fixture for testing a semiconductor die comprising:

a first plate for receiving the die;

a second plate attached to the first plate for retaining the die on the first plate; and

a tape for electrically connecting the die to test circuitry, the tape comprising a plastic film, a bump on the film for physically and electrically contacting a contact on the die, a conductive trace on the film in electrical communication with the bump, and an electrical connector in electrical communication with the trace and connectable to the test circuitry;

a compressible elastomeric pad placed between the first plate and the second plate for biasing the bump against the contact;

with a first portion of the film placed between the first plate and the second plate and biased against the die by the pad;

with a second portion of the film and the connector extending beyond a confine of the fixture, and with the bump, the trace, and the connector providing an electrical path independent of the first plate and the second plate, from the test circuitry to the contact on the die.

Clean Version Of All Pending Claims

34. (amended) A test fixture for testing a semiconductor die comprising:

a first plate for receiving the die;

a second plate attached to the first plate for retaining the die therebetween; and

a tape placed between the first plate and the second plate for electrically connecting the die to test circuitry, the tape comprising a plastic film, a bump on the film for physically and electrically contacting a contact on the die, a conductive trace on the film in electrical communication with the bump, and an electrical connector in electrical communication with the trace and connectable to the test circuitry;

with the connector, and at least a portion of the trace extending beyond a confine of the fixture, and with the bump, the trace, and the connector configured to provide a direct electrical path from the test circuitry to the contact on the die.

35. (amended) The fixture of claim 34 wherein the film comprises polyimide.

36. The fixture of claim 34 wherein the first plate comprises a die receiving cavity sized to receive the die.

37. The fixture of claim 34 further comprising an elastomeric biasing member placed between the first plate and the second plate for biasing the bump against the contact.

38. The fixture of claim 34 further comprising a clamp for securing the first plate to the second plate.

39. (amended) A test fixture for testing a semiconductor die comprising:

a first plate for receiving the die;
a second plate attached to the first plate for retaining the die on the first plate; and

a tape for electrically connecting the die to test circuitry, the tape comprising a plastic film, a bump on the film for physically and electrically contacting a contact on the die, a conductive trace on the film in electrical communication with the bump, and an electrical connector in electrical communication with the trace and connectable to the test circuitry;

with a first portion of the film placed between the first plate and the second plate and biased against the die;

with a second portion of the film and the connector extending beyond a confine of the fixture, and with the bump, the trace and the connector providing a direct electrical path from the test circuitry to the contact on the die.

40. The test fixture of claim 39 further comprising a compressible elastomeric pad placed between the first plate and the second plate to bias the first portion of the film against the die.

41. The test fixture of claim 39 wherein the film comprise polyimide and the bump comprises solder.

43. (amended) A test fixture for testing a semiconductor die comprising:

a first plate for receiving the die;
a second plate attached to the first plate for retaining the die on the first plate; and

a tape for electrically connecting the die to test circuitry, the tape comprising a plastic film, a bump on the film for physically and electrically contacting a contact on the die, a conductive trace on the film in electrical communication with the bump, and an electrical connector in

electrical communication with the trace and connectable to the test circuitry;

a compressible elastomeric pad placed between the first plate and the second plate for biasing the bump against the contact;

with a first portion of the film placed between the first plate and the second plate and biased against the die by the pad;

with a second portion of the film and the connector extending beyond a confine of the fixture, and with the bump, the trace, and the connector providing an electrical path independent of the first plate and the second plate, from the test circuitry to the contact on the die.

44. The test fixture of claim 43 wherein the bump comprises a material selected from the group consisting of metal and a conductive polymer.

45. The test fixture of claim 43 wherein the first plate includes a cavity for retaining the die.

46. The test fixture of claim 43 wherein the first plate includes a cavity and a spacer member within the cavity for retaining the die.